
GLOSSARY OF TECHNICAL TERMS

This glossary of technical terms contains terms used in this prospectus in connection with the Group. As such, these terms and their meanings may not correspond to standard industry meaning or usage of these terms.

“ACF”	acronym for anisotropic conductive film, fine pitch heat seal technology, film type adhesive dispersed with metal coating particles
“CCD”	acronym for charged couple device, a dedicated semiconductor consisting of individual light-collection elements called pixels that collect and transfer light to other system chips
“CMOS”	acronym for complementary metal oxide semiconductor, a light-collecting chip that also incorporates other functionality onto it (for example, analog conversion to digital functionality and color processing) and is manufactured using a common manufacturing technique that is used to produce many other kinds of signal processors
“COB”	acronym for chip on board, a technology that utilises wire bonding to connect large-scale integrated circuits directly to printed circuit boards
“COF”	acronym for chip on film, an assembly method for bonding integrated circuit chips and other components onto a flexible printed circuit
“COG”	acronym for chip on glass, a process that connects integrated circuits directly to LCD panels without the need for wire bonding
“CSP”	acronym for chip scale packaging, a CSP has an area of no more than 1.2 times the area of the original die size and is direct surface mountable
“EMS”	acronym for electronics manufacturing services
“FPC”	acronym for flexible printed circuit, a patterned arrangement of printed wiring utilising flexible base material with or without flexible cover layers
“FPHS”	acronym for fine pitch heat seal technology, a technology used to connect LCD displays to printed circuit boards produced by chip on board or outer lead bonding that enable very thin connections
“GPS”	global positioning system
“image sensor”	acronym for light-sensing semiconductors that translate analog light and color gathered by the lens into a digital signal that can be processed by the device

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“LCD”	acronym for liquid crystal display, a technology used for flat panel displays
“MP”	acronym for megapixel, the number of lightsensing diodes, in millions of units, on the image sensor
“ODM”	acronym for original design manufacturer
“OLB”	acronym for outer lead bonding, an advanced technology used to connect printed circuit boards and large-scale integrated circuits with a large number of connectors
“PCB”	acronym for printed circuit board, a flat board made of non-conductive material, such as plastic or fibreglass, on which chips and other electronic components are mounted, usually in predrilled holes designed to hold them. The component holes are connected electrically by predefined conductive metal pathways that are printed on the surface of the board. The metal leads protruding from the electronic components are soldered to the conductive metal pathways to form a connection
“PDA”	acronym for personal digital assistant, a pocket-sized, special purpose personal computer that lacks a conventional keyboard
“RF”	acronym for radio frequency
“SKD form”	acronym for semi-knocked down form
“SMT”	acronym for surface mount technology, a process by which electronic components are mounted directly on both sides of a printed circuit board, increasing board capacity, facilitating product miniaturisation and enabling advanced automation of production
“TAB”	acronym for tape automated bonding, a high pin count flexible packaging format for integrated circuits
“USB”	acronym for universal serial bus, a plug-and-play interface between a computer and add-on devices (such as audio players, joysticks, keyboards, telephones, scanners, and printers) which allows a new device to be added to a computer without having to add an adapter card or having to turn the computer off